



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

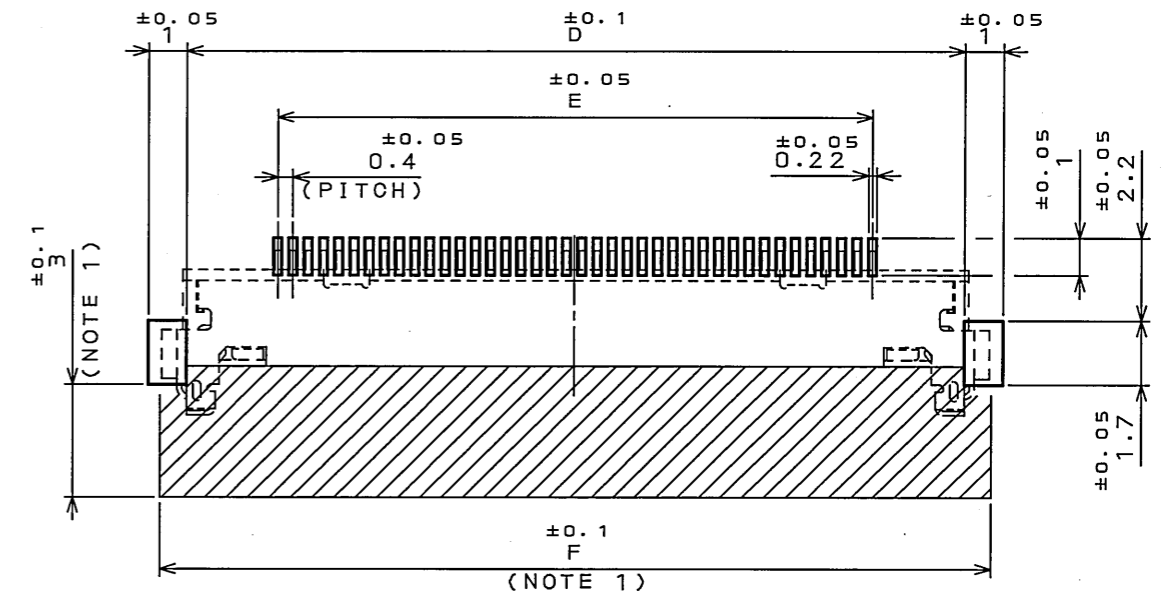
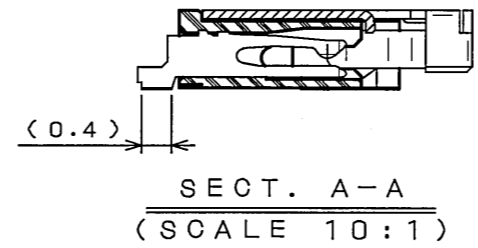
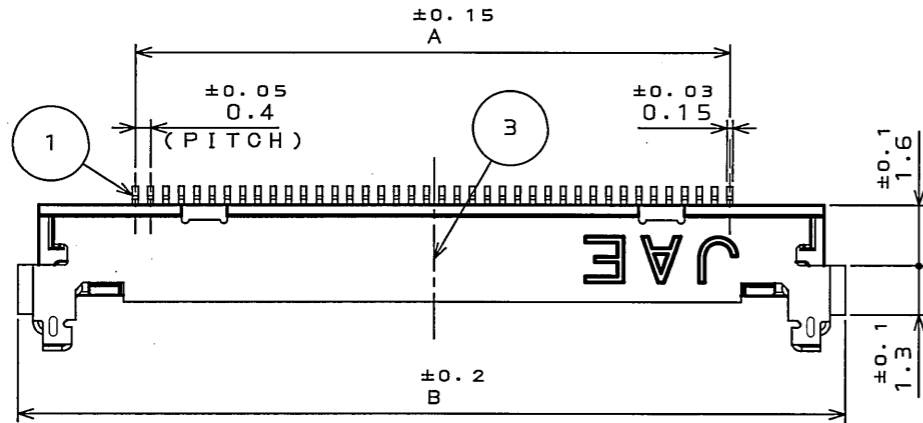
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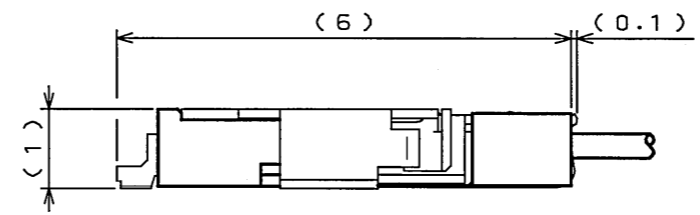
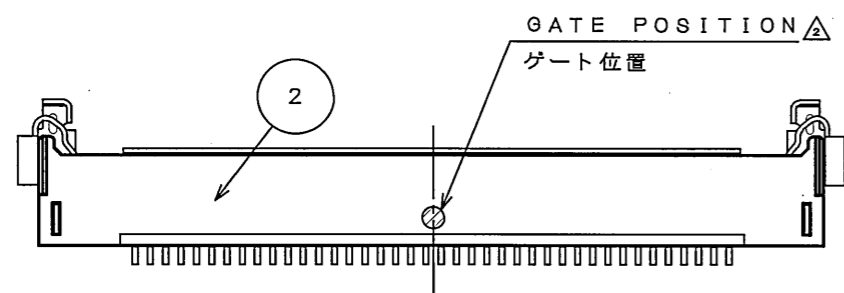
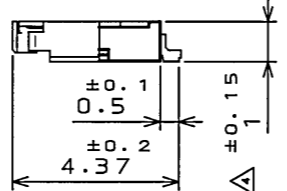
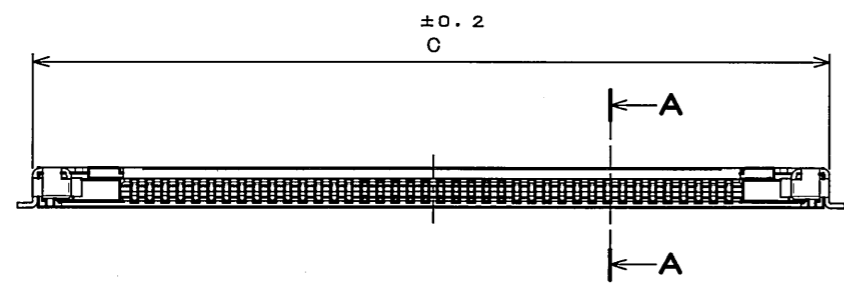
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



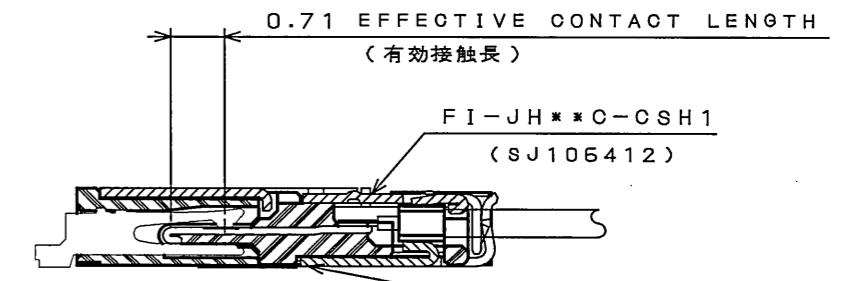
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	23.Oct.2006	061405	ADDING PRODUCT NAME AND GATE POSITION		T.TSUJI		Y.TATEBE
3	30.Oct.2006	061457	ERROR CORRECTION		T.TSUJI	M.SUZUKI	K.HISATOMI
4	1.Feb.2008	064958	REVISED TOLERANCE		T.TSUJI	M.KIKUCHI	K.HISATOMI



APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法 (参考)



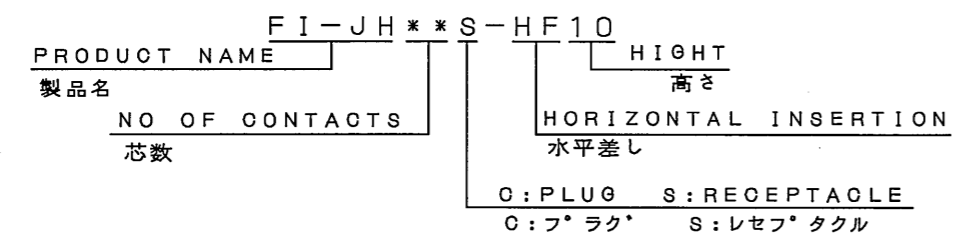
MATED CONDITION (REF.)
嵌合状態 (参考)



SECT. OF MATED CONDITION (REF.)
嵌合状態断面図 (参考)

Pin NO.	A	B	C	D	E	F
40	15.6	21.7	20.9	20.4	15.6	21.8
30	11.6	17.7	16.9	16.4	11.6	17.8

NOTE 1. THIS AREA IS GROUND-PATTERN ONLY.
2. COPLANARITY BETWEEN TERMINAL AND HOLD DOWN SHOULD BE 0.1mm MAX.
3. PRODUCT NAME IS MARKED AS SHOWN IN BELOW FIGURE MARKING.
注 1. この範囲は、プラグコネクタのシェルが接触する為、パターン及びスルーホール不可とする。但し、グランドは可とする。
2. 端子および、ホールダウンの相互のパラツキは0.1mm以内とする。
3. 製品名の表記方法は下記による。



3	COVER SHELL カバーシェル	1	STAINLESS STEEL ステンレス	CONTACT AREA: GOLD(0.03μmMIN) OVER NICKEL 接触部: NI上Au(0.03μm以上)メッキ	
2	INSULATOR インシュレータ	1	HAET RESISTING PLASTIC 耐熱性樹脂		
1	CONTACT コンタクト	**	COPPER ALLOY 銅合金	CONTACT AREA: GOLD(0.1μmMIN) OVER NICKEL 接触部: NI上Au(0.1μm以上)メッキ	TERMINAL AREA: GOLD(0.03μmMIN) OVER NICKEL
仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE) 20.Jun.2006	尺度 (SCALE) 5:1	シリーズ (SERIES) FI-JH	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
一般公差 (GENERAL TOLERANCE)	製図 DR. H.ABE	名称 (TITLE) FI-JH***S-HF10			
寸法 (DIMENSION) 角度 (ANGLES)	担当 CHK. T.TSUJI	(PCB SIDE)			
公差 (DIMENSION) 角度 (ANGLES)	査閲 APPD. M.KIKUCHI				
公差 (DIMENSION) 角度 (ANGLES)	承認 APPD. K.HISATOMI				
質量 (MASS)				図面番号 (DRAWING NO.) SJ106787	版数 (REV.) 4

DOF-0-212F(05.08)

